



Solid State Devices, Inc.

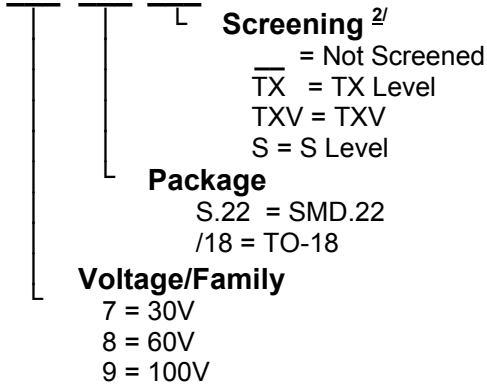
14701 Firestone Blvd * La Mirada, CA 90638
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SFS3027 - SFS3029 Series

Designer's Data Sheet

Part Number/Ordering Information ^{1/}

SFS302



**0.5 AMP, 30 - 100 Volt
FAST SWITCHING
SILICON CONTROLLED
RECTIFIER**

FEATURES:

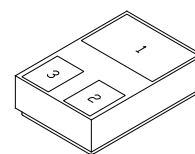
- Passivated Planar Construction
- Low On-State Voltage and Fast Switching
- Hermetically Sealed Surface Mount Power Package
- Replacement for 2N3027 – 2N3029 Series - Contact Factory for Additional SCR Products

MAXIMUM RATINGS ^{3/}		Symbol	Value	Units
Peak Repetitive Reverse Voltage and DC Blocking Voltage	SFS3027	V_{DRM}	30	Volts
	SFS3028	V_{RRM}	60	
	SFS3029		100	
Non-Repetitive Peak Reverse Blocking Voltage (t < 5.0 ms)	SFS3027	V_{RSM}	50	Volts
	SFS3028		100	
	SFS3029		200	
RMS On-State Current, (All Conduction Angles, T _C = 100°C)		$I_T (RMS)$	0.5	Amps
Peak Non-Repetitive Surge Current (One Cycle, 60 Hz)		I_{TSM}	8	Amps
Peak Gate Power		P_{GM}	0.1	Watts
Average Gate Current		$I_{G(ave)}$	0.025	Amps
Peak Gate Current		I_{GM}	0.25	Amps
Reverse Gate Current		I_{GR}	0.003	Amps
Reverse Gate Voltage		V_{GM}	5.0	Volts
Operating Junction Temperature Range		T_J	-65 to +150	°C
Storage Temperature Range		T_{stg}	-65 to +200	°C
Thermal Resistance, Junction to Case		$R_{\theta JC}$	15	°C/W

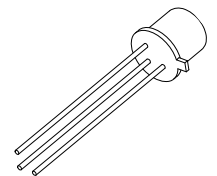
NOTES:

- 1/ For ordering information, price, operating curves, and availability- Contact factory.
- 2/ Screening based on MIL-PRF-19500. Screening flows available on request.
- 3/ Unless otherwise specified, all electrical characteristics @25°C.

SMD.22



TO-18



NOTE: All specifications are subject to change without notification. SCD's for these devices should be reviewed by SSDI prior to release.

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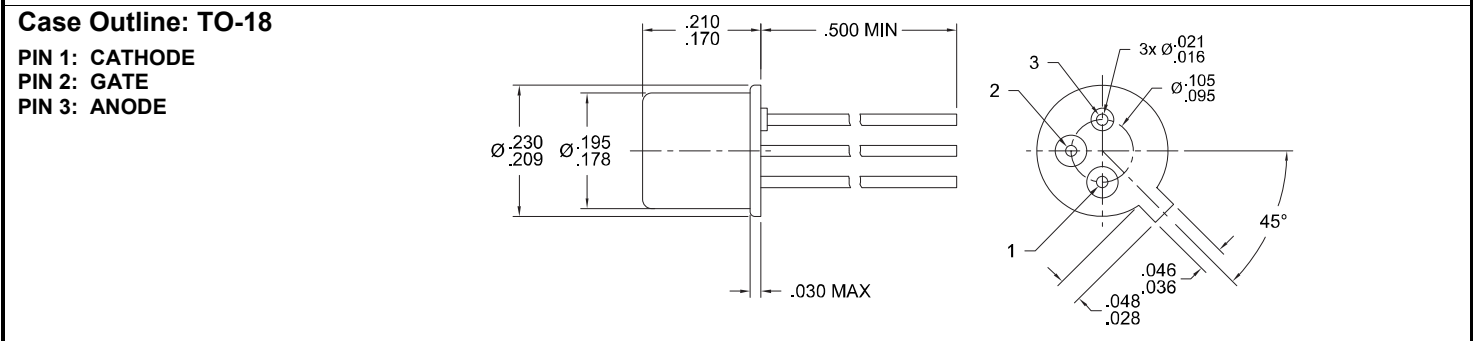
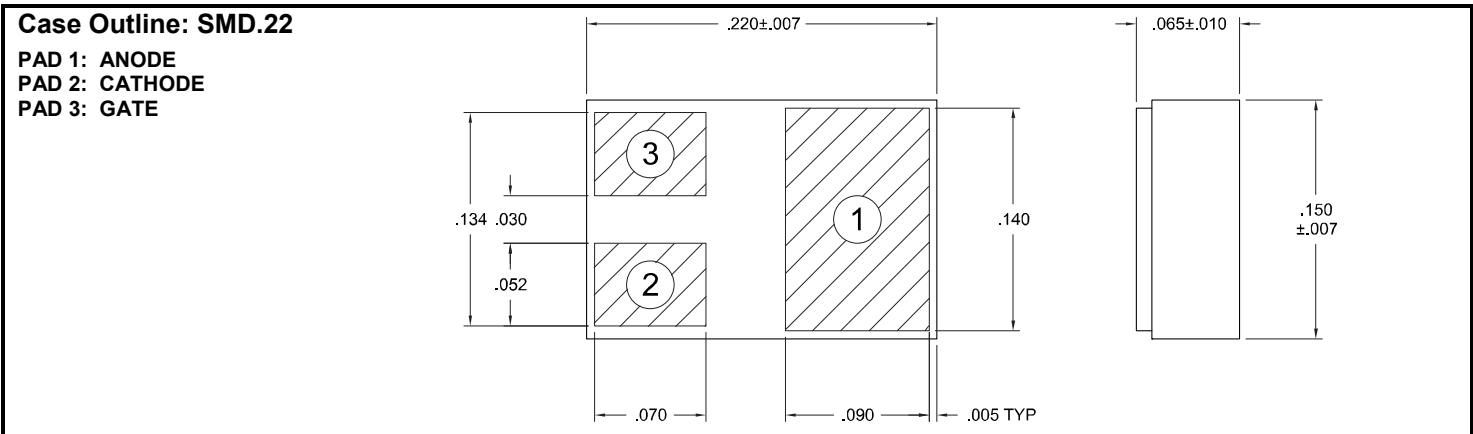


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Series**

ELECTRICAL CHARACTERISTICS ^{3/}		Symbol	Min	Typical	Max	Unit
Peak Reverse Blocking Current Rated V_{RRM} , $R_{GK} = 1000 \Omega$	$T_C = 25^\circ C$ $T_C = 150^\circ C$	I_{RRM}	—	0.08 20	0.1 50	μA
Peak Forward Blocking Current Rated V_{DRM} , $R_{GK} = 1000 \Omega$	$T_C = 25^\circ C$ $T_C = 150^\circ C$	I_{DRM}	—	0.08 30	0.1 50	μA
Peak On-State Voltage $I_F = 1.0 A$ pulse		V_{TM}	0.8	1.1	1.5	V
Gate Trigger Current $V_D = 5 V_{DC}$, $R_L = 100 \Omega$, $R_e = 10 k\Omega$	$T_C = 25^\circ C$ $T_C = -65^\circ C$	I_{GT}	— —	25 50	200 1200	μA
Gate Trigger Voltage $V_D = 5 V_{DC}$, $R_L = 100 \Omega$, $R_e = 100 \Omega$	$T_C = 25^\circ C$ $T_C = -65^\circ C$ $T_C = 150^\circ C$	V_{GT}	0.4 0.6 0.1	0.55 0.75 0.20	0.8 1.1 0.6	V
Holding Current $V_D = 5 V_{DC}$, $R_{GK} = 1000 \Omega$	$T_C = 25^\circ C$ $T_C = -65^\circ C$ $T_C = 150^\circ C$	I_H	0.3 0.5 0.05	1.0 1.5 0.38	5.0 10.0 1.0	mA
Off-State Voltage-Critical Rate of Rise		dv_c/dt	30	—	—	V/ μs
Gate Trigger-on Pulse Width Per Fig. 1		$t_{pg(on)}$	—	0.25	0.40	μs
Gate Trigger-on Delay Time Gate Trigger-on Rise Time Per Fig. 1 with C1 = 0 and C2 = 0		t_d t_r	— —	0.10 0.75	— —	μs





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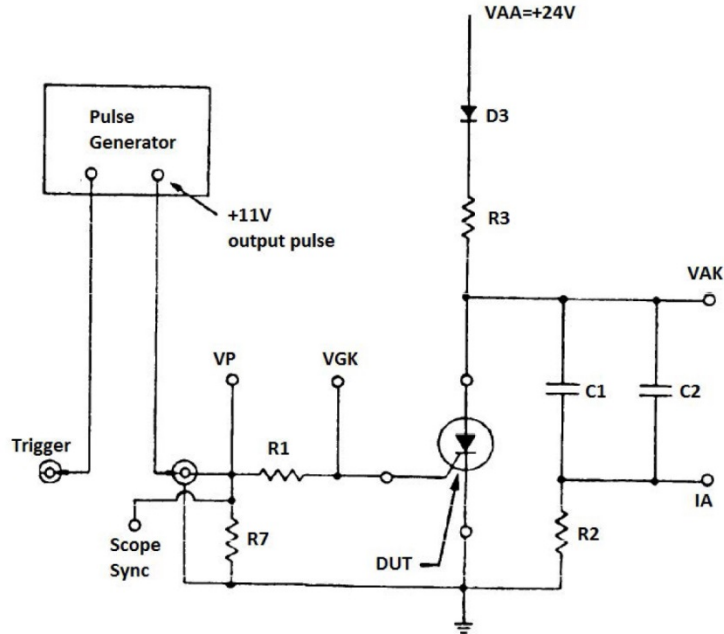


Fig. 1 Test Circuit for tpg(on), td and tr

Legends of circuit Element: R1=1k, R2=30 non-inductive, R3=500 2W, R7=56, C1=1uF, C2=0.1uF ceramic, D3=1N457A (optional)

tpg(on) Test Procedure:

1. Can use DC or pulsating AC 60Hz for VAA. If VAA is pulsating AC then D3 must be used, and trigger to Pulse Gen should be synchronized.
2. With specified VAA, IF and IGF initially established, connect a high frequency oscilloscope vertical input to the IA monitor point. The width of the gate current pulse is then set to a value that causes triggering to occur. The pulse width at this point is the gate trigger-on pulse width.
3. For additional details, see Mil-S-19500/419(EL).

td and tr Test Procedure:

1. Remove C1 and C2, and set gate pulse width >2us.
2. Measure td from leading edge of gate pulse to 10% of VAK falling edge.
3. Measure tr from 10% to 90% of VAK falling edge.

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